# EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L6 | 35 | (circuit IC die chip) near (lid cover) with (project$3 protrud$3) with engag$3 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/09/10 08:42 |
| L7 | 3 | ("4580157" \| "4975762" \| "5268533").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/10 08:41 |
| L8 | 0 | ("6611054").URPN. | USPAT | OR | ON | 2007/09/10 08:41 |
| L9 | 1035 | attach$4 and detach$4 and (circuit IC die chip) near (lid cover) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/09/10 08:44 |
| L10 | 25017133 | @ad<"20031007" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/09/10 10:38 |
| L11 | 552 | L9 and L10 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/09/10 08:45 |
| L12 | 1500 | 257/704.ccls. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/09/10 09:08 |
| L13 | 1231 | L12 and L10 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/09/10 10:14 |
| L14 | 11 | ("20010008776" \| "20020175421" \| "20020195270" \| "5424573" \| "5616957" \| "5977626" \| "6414385" \| "6437984" \| "6608763" \| "6703698" \| "6734552").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/10 09:18 |

| L15 | 2 | ("5583373" \| "5610431").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/10 09:28 |
|---|---|---|---|---|---|---|
| L16 | 8 | ("4417392" \| "4901136" \| "4954878" \| "5012323" \| "5095359" \| "5220195" \| "5223741" \| "5237204").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/10 09:29 |
| L17 | 3308 | (lid cover) with attach$4 with detach$4 with (device chip die IC circuit) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:19 |
| L18 | 2170 | L17 and L10 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:16 |
| L19 | 139 | 18 and substrate | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:16 |
| L20 | 139 | (lid cover) with attach$4 with detach$4 with (device chip die IC circuit) near (substrate board wafer) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:39 |
| L21 | 95 | (lid cover) with attach$4 near detach$4 with (device chip die IC circuit) near (substrate board wafer) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:38 |
| L22 | 33608 | (lid cover) with (device chip die IC circuit) near (substrate board wafer) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:38 |
| L23 | 24330 | 22 and @ad<"20031007" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:38 |

| L24 | 844 | 23 and attach$4 with detach$4 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:40 |
|-----|-----|-------------------------------|-----------------------------------------------------------|----|----|------------------|
| L25 | 0   | 24 and semocnductor           | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:47 |
| L26 | 192 | 24 and semiconductor          | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:47 |
| L27 | 215 | 24 and packag$3               | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2007/09/10 10:51 |